ABSTRACT

INTEGRATED CIRCUIT SYSTEM WITH VIA AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit system includes: forming an etch stop layer over a bulk substrate; forming a buffer layer on the etch stop layer; forming a hard mask on the buffer layer; forming a through silicon via through the etch stop layer with the hard mask detected and the buffer layer removed with a low down force; and forming a passivation layer on the through silicon via and the etch stop layer.

Fig. 2